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HOSTAFORM® C 13021 XAP®2

POM copolymer Medium flow injection molding grade with reduced emissions especially for automotive interior application. Burning rate according to FMVSS 302 < 100 mm/min (1 mm thickness) Emission according to VDA 275 < 2 mg/kg (natural grades) Emission according to VDA 275 < 5 mg/kg (colored grades)

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Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469
Rheological properties			
Melt volume-flow rate		cm ³ /10min	ISO 1133
Temperature	190		
Load	2.16	-	
Moulding shrinkage, parallel	2.0		ISO 294-4, 2577
Moulding shrinkage, normal	1.8	%	ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus	2750	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	64	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9	%	ISO 527-1/-2
Nominal strain at break	25	%	ISO 527-1/-2
Flexural modulus	2700		ISO 178
Tensile creep modulus, 1h	2400		ISO 899-1
Tensile creep modulus, 1000h	1200		ISO 899-1
Charpy impact strength, 23°C		kJ/m²	ISO 179/1eU
Charpy impact strength, -30 °C		kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C		kJ/m ²	ISO 179/1eA
Charpy notched impact strength, -30°C Poisson's ratio	0.37 ^[C]	kJ/m²	ISO 179/1eA
	0.37		
[C]: Calculated			
Thermal properties			
Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Coefficient of linear thermal expansion	120	E-6/K	ISO 11359-1/-2
(CLTE), parallel			
Coefficient of linear thermal expansion (CLTE),	120	E-6/K	ISO 11359-1/-2
normal Flammability			
•		, .	100 (51 11/00)
Burning rate, Thickness 1 mm	44./	mm/min	ISO 3795 (FMVSS 302)
Electrical properties			
Relative permittivity, 100Hz	4		IEC 62631-2-1
Relative permittivity, 1MHz	4		IEC 62631-2-1
Dissipation factor, 100Hz		E-4	IEC 62631-2-1
Dissipation factor, 1MHz		E-4	IEC 62631-2-1
Volume resistivity		Ohm.m	IEC 62631-3-1
Surface resistivity	1E14	_	IEC 62631-3-2
Electric strength	35	kV/mm	IEC 60243-1

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Comparative tracking index	600	IEC 60112
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Physical/Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	0.65 %	Sim. to ISO 62
Density	1410 kg/m³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	190	°C
Min. melt temperature	180	°C
Max. melt temperature	200	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	4	MPa

Characteristics

Processing Injection Moulding

Delivery form Pellets

Special characteristics Low emissions

Additional information

Injection molding Preprocessing

To achive low emission values pre drying using a recirculating air dryer (100 to $120 \, ^{\circ}\text{C}$ / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,1 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Processing Notes Pre-Drying

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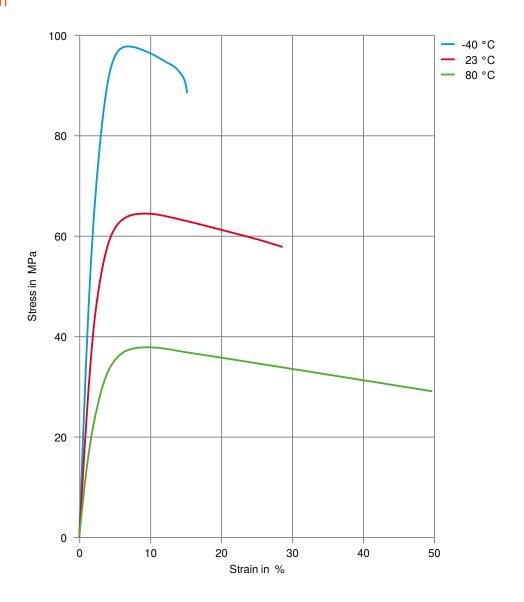
recommended

Automotive

OEM STANDARD ADDITIONAL INFORMATION
Mercedes-Benz DBL5404 BQF

VW Group TL 524 76

Stress-strain



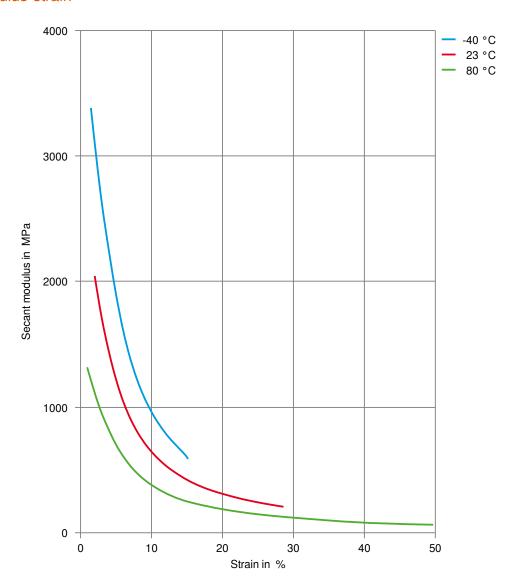
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Secant modulus-strain



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